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## Bulletin

We hereby certify that the resins below produced by CHIMEI Corporation

**POLYLAC® ABS**                      **PA-763, PA-763A, PA-764, PA-764B, PA-764G, PA-765, PA-765 J01, PA-765A, PA-765A J01, PA-765B, PA-765B J01**

conforms to the requirement that no chemicals as following are intentionally added.

1. PBDEs (Polybrominated Diphenyl Ethers)
2. PBBs (Polybrominated Biphenyls)
3. Ozone Depleting Chemicals (CFCs & HCFCs)
4. Chlorinated Paraffin (C10-C13)
5. Polyvinyl Chloride (PVC)
6. Mercury (Hg) and its compounds
7. Lead (Pb) and its compounds
8. Cadmium (Cd) and its compounds
9. Chromium (Cr) and its compounds
10. Arsenic (As) and its compounds
11. Selenium (Se) and its compounds
12. Barium (Ba) and its compounds
13. Beryllium (Be) and its compounds
14. Bismuth (Bi) and its compounds
15. Organic tin compounds (TBT, TPT, DOT, DBT)
16. Polychlorinated Biphenyls (PCBs) and Terphenyls (PCTs) and Napthalenes (PCNs)
17. Poly naphthalenes
18. Azo colorants (according to REACH-ANNEX-XVII-APPENDIX 8)
19. Asbestos
20. Phthalates
21. APEO: Including Alkylphenol(AP), Octylphenol(OP), Nonylphenol(NP), Octylphenol ethoxylates(OPE), Nonylphenol ethoxylates(NPE)
22. 2-(2'-Hydroxy-3',5'-di-tert-butylphenyl)benzotriazole
23. PFOA, PFOS
24. Bisphenol A
25. Formaldehyde
26. Dimethylfumarate (DMF)
33. Dioxins and furans
34. Primary aromatic amines (PAA)
35. Perchlorate
36. Hexachlorobenzene
37. Mirex
38. Specified amine compounds
39. Benzene
40. Benzenamine, *N*-phenyl-, Reaction Products with Styrene and 2,4,4-Trimethylpentene (BNST)
41. Polyamide
42. PVDC (polyvinylidene chloride)
43. ESBO (Expoxidized soybean oil)
44. Formamide
45. Hexabromocyclododecane (HBCDD)
46. Red phosphorus
47. Aniline · formaldehyde polycondensate
48. Tris (2,3-dibromopropyl) phosphate
49. Tris (aziridinyl) phosphin oxide
50. Tri-*o*-cresyl phosphate
51. Tris (2-chloroethyl) phosphate (TCEP)
52. Tris (2-chloro-1-methylethyl) phosphate (TCPP)
53. Tris (1,3-Dichloro-2-propyl) phosphate (TDCPP)
54. 4,4'-Sulfonyldiphenol (BPS)
55. PIP (3:1) (phenol, isopropylated phosphate 3:1)
56. DecaBDE (decabromodiphenyl ether)
57. 2,4,6-TTBP (2,4,6-Tris(tert-butyl)phenol)
58. HCBd (hexachlorobutadiene)
59. PCTP (pentachlorothiophenol)

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With regard to composition of above grades of products, the aforesaid products comply with the Directives of RoHS (2011/65/EU), 2003/11/EC, TCO'07, Blue Angel and SONY Standard (SS-00259).

Sincerely Yours,

  
Perry D. B. Shueh  
Vice President of R&D Division

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